



<b>PCN Number:</b>	20190820006	<b>PCN Date:</b>	Aug. 30, 2019
<b>Title:</b>	Datasheet for TLIN1029-Q1 and TLIN2029-Q1		
<b>Customer Contact:</b>	PCN Manager	<b>Dept:</b>	Quality Services
<b>Change Type:</b>			
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Site	
<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Material	
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Bump Process	
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Site	
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Materials	
		<input type="checkbox"/> Wafer Fab Process	
<b>Notification Details</b>			
<b>Description of Change:</b>			
<p>Texas Instruments Incorporated is announcing an information only notification.  The product datasheet(s) is being updated as summarized below.  The following change history provides further details.</p>			
		<b>TLIN1029-Q1</b> <small>SLLSEY5C – OCTOBER 2017 – REVISED JULY 2019</small>	
<b>Changes from Revision B (February 2018) to Revision C</b>			<b>Page</b>
<ul style="list-style-type: none"> <li>Changed the SOIC package Body Size From: 4.90 mm x 6.00 mm To: 4.90 mm x 3.91 mm in the <i>Device Information</i> ..... 1</li> <li>Changed the 220 pF capacitor To: 200 pF in the <i>Simplified Schematics, Master Mode</i> ..... 1</li> <li>Changed the 220 pF capacitor To: 200 pF in the <i>Simplified Schematics, Slave Mode</i> ..... 1</li> <li>Changed <math>V_{\text{LOGIC}}</math> absolute maximum rating MAX from 5.5 V to 6 V ..... 4</li> <li>Changed the 220 pF capacitor To: 200 pF in <a href="#">Figure 30</a> ..... 24</li> <li>Changed the title of <a href="#">Figure 31</a> To: Recessive to Dominant Propagation ..... 25</li> <li>Changed the title of <a href="#">Figure 32</a> To: Dominant to Recessive Propagation ..... 25</li> <li>Changed text From: "For slave applications a 220 pF capacitor" To: "For slave applications a 200 pF capacitor" For Pin 6 (LIN) in the <i>Layout Guidelines</i> ..... 26</li> </ul>			
		<b>TLIN2029-Q1</b> <small>SLLSEY6C – OCTOBER 2017 – REVISED JULY 2019</small>	
<b>Changes from Revision B (February 2018) to Revision C</b>			<b>Page</b>
<ul style="list-style-type: none"> <li>Changed the SOIC package Body Size From: 4.90 mm x 6.00 mm To: 4.90 mm x 3.91 mm in the <i>Device Information</i> ..... 1</li> <li>Changed the 220 pF capacitor To: 200 pF in the <i>Simplified Schematics, Master Mode</i> ..... 1</li> <li>Changed the 220 pF capacitor To: 200 pF in the <i>Simplified Schematics, Slave Mode</i> ..... 1</li> <li>Changed <math>V_{\text{LOGIC}}</math> absolute maximum rating MAX from 5.5 V to 6 V ..... 4</li> <li>Changed the 220 pF capacitor To: 200 pF in <a href="#">Figure 23</a> ..... 24</li> <li>Changed the title of <a href="#">Figure 24</a> To: Recessive to Dominant Propagation ..... 25</li> <li>Changed the title of <a href="#">Figure 25</a> To: Dominant to Recessive Propagation ..... 25</li> <li>Changed text From: "For slave applications a 220 pF capacitor" To: "For slave applications a 200 pF capacitor" For Pin 6 (LIN) in the <i>Layout Guidelines</i> ..... 26</li> </ul>			

The datasheet number will be changing.

Device Family	Change From:	Change To:
TLIN1029-Q1	SLLSEY5B	SLLSEY5C
TLIN2029-Q1	SLLSEY6B	SLLSEY6C

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/TLIN1029-Q1>

<http://www.ti.com/product/TLIN2029-Q1>

#### Reason for Change:

To accurately reflect device characteristics.

#### Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

#### Changes to product identification resulting from this PCN:

None.

#### Product Affected:

TLIN1029DQ1	TLIN1029DRBRQ1	TLIN1029DRBTQ1	TLIN1029DRQ1
TLIN1029MDRBRQ1	TLIN2029DQ1	TLIN2029DRBRQ1	TLIN2029DRBTQ1
TLIN2029DRQ1			

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
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